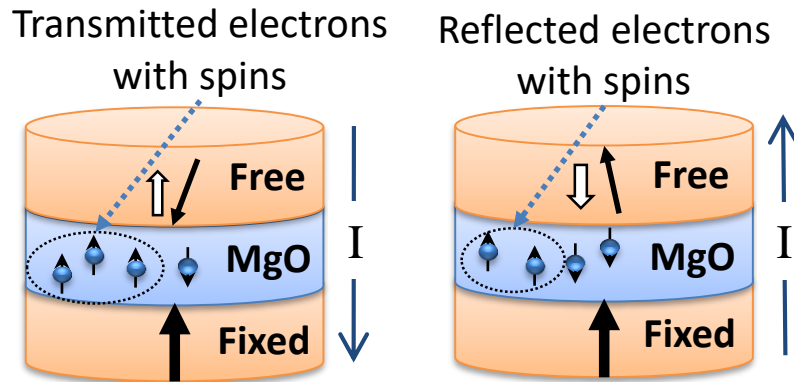


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*University of California, Los Angeles*

# **VARIATION MONITOR-ASSISTED ADAPTIVE MRAM WRITE**

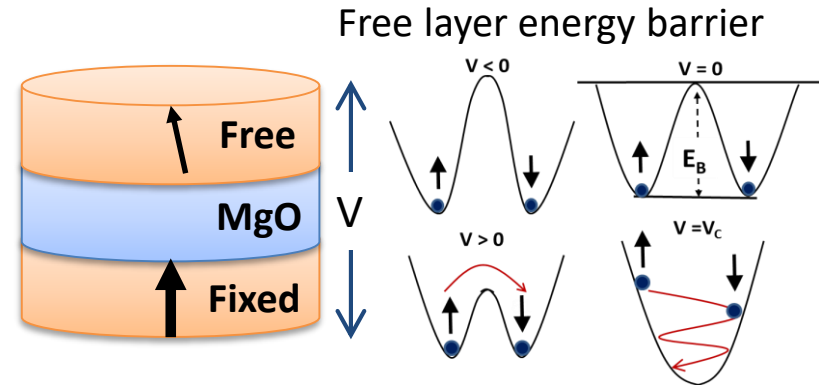
# Write mechanism of STT-RAM and MeRAM

## Spin-torque transfer magnetic tunnel junction (STT-MTJ)



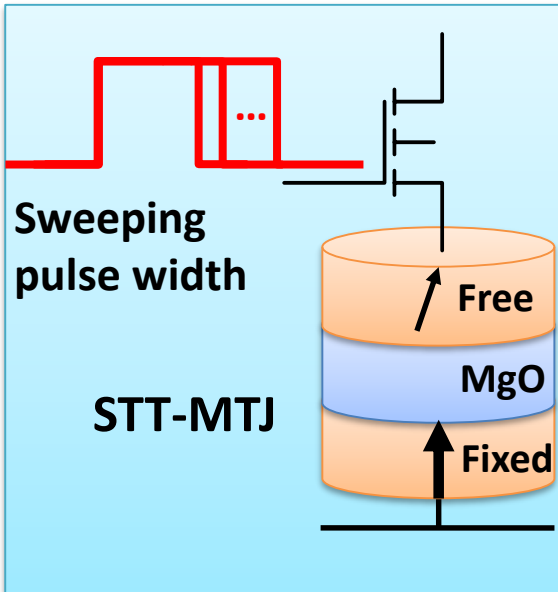
- STT-MTJ write
  - Bi-directional current-driven
  - Critical current density ( $J_c$ )
  - Deterministic write
  - **Slow (5~10ns)**
  - **High power (0.2pJ~1 pJ/bit) due to low MTJ resistance (1k-10k  $\Omega$ )**

## Voltage-control magnetic tunnel junction (VC-MTJ)

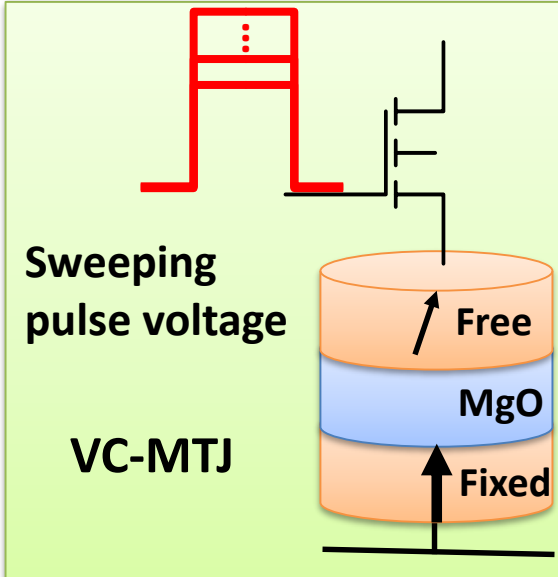
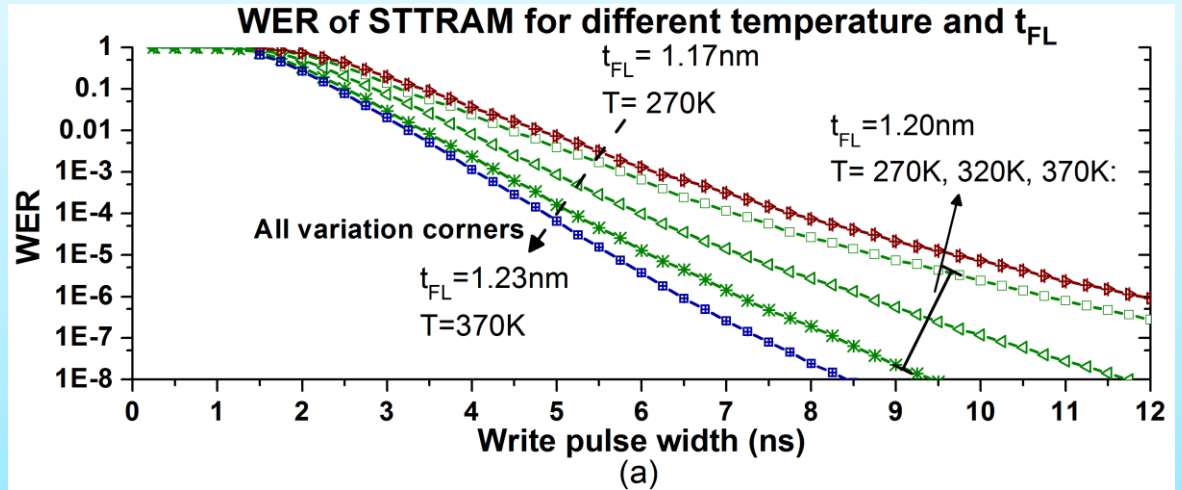


- VC-MTJ write
  - Uni-directional voltage-driven
  - Critical voltage ( $V_c$ )
  - **Non-deterministic write (leads to write errors)**
  - Fast (~1ns)
  - Low power (10~50 fJ/bit) due to high MTJ resistance (20k-200k  $\Omega$ )

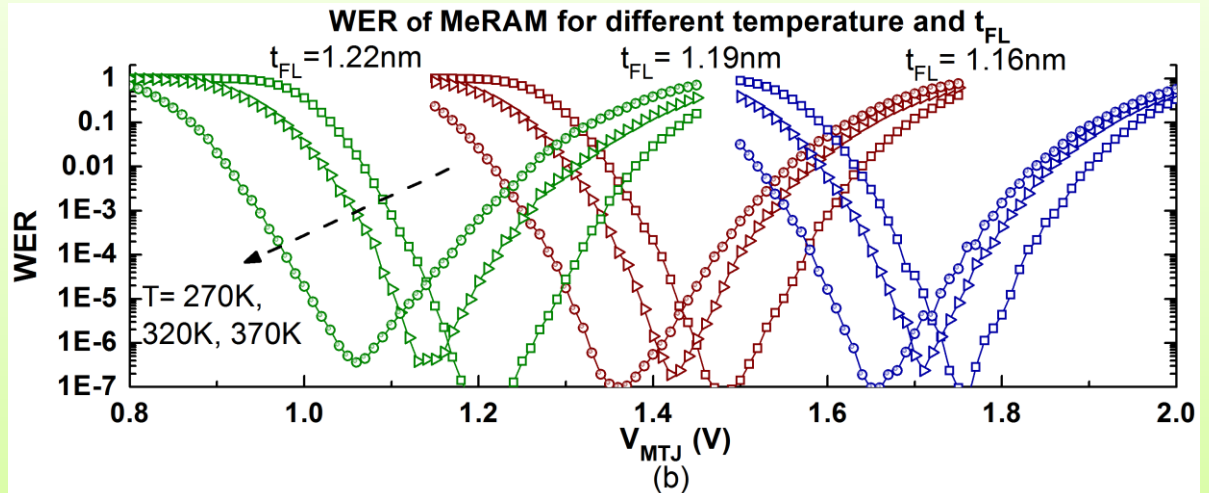
# MRAM write error rate (WER) under variation



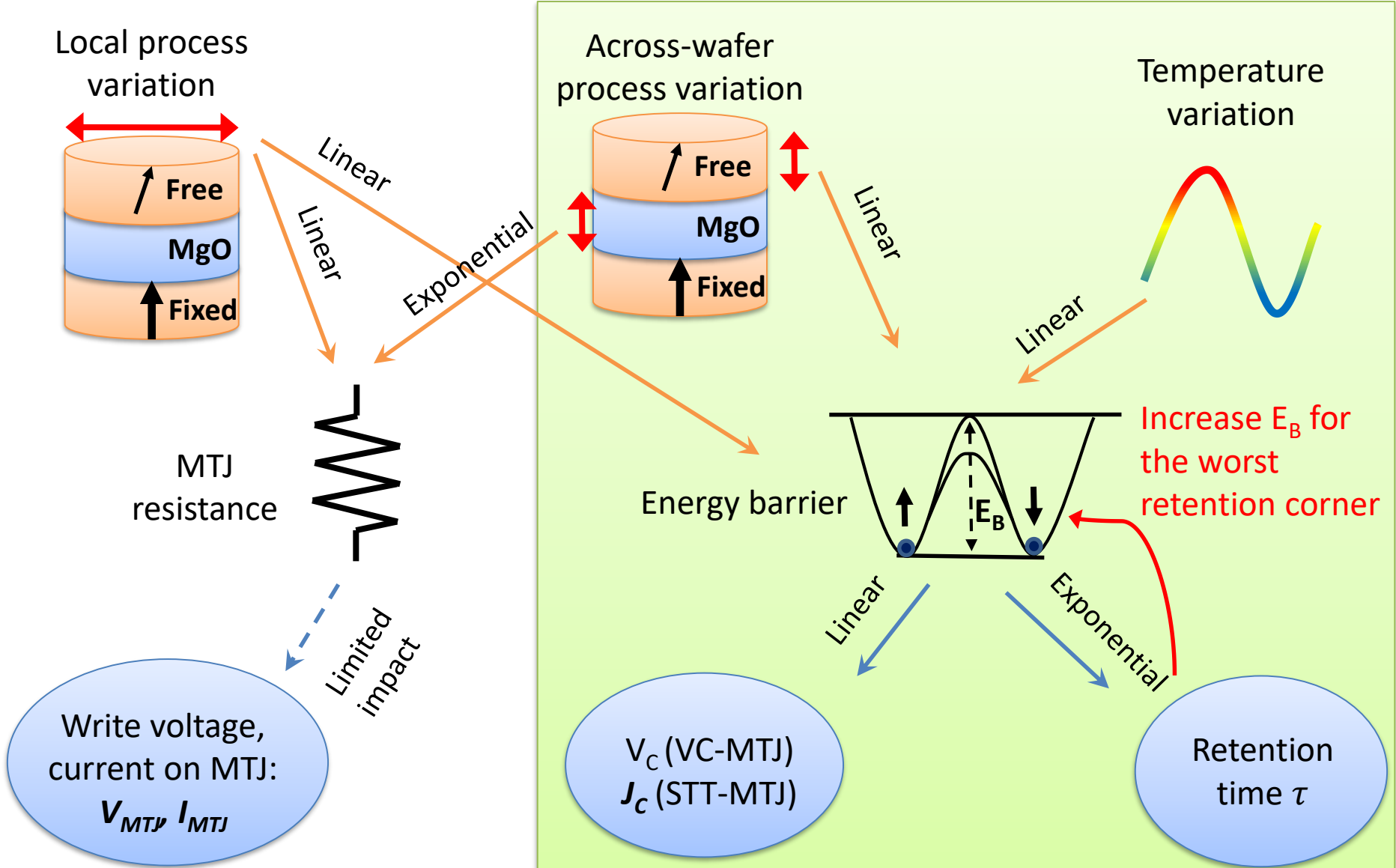
## Spin-transfer torque RAM (STT-RAM)



## Magnetoelectric RAM (MeRAM)



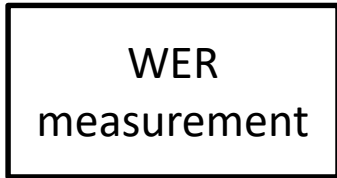
# MRAM write under variation



# Sensing write behavior change under variation

30°C changes WER from  $10^{-6}$  to  $10^{-4}$  → High energy and long delay

Straight-forward sensing method



Many write and read tests

$V_C$ ,  $J_C$  change under variation

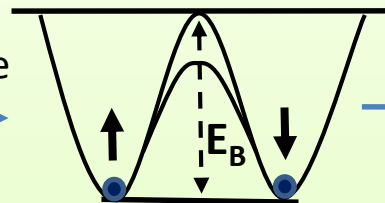
Sensing through thermal activation

Thermal activated switching rate

Exponential dependence

Retention time  $\tau$

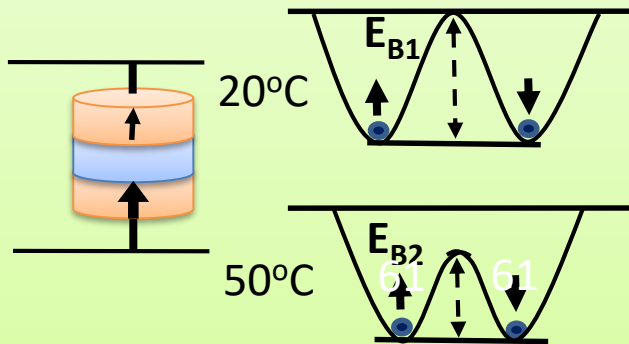
Exponential dependence



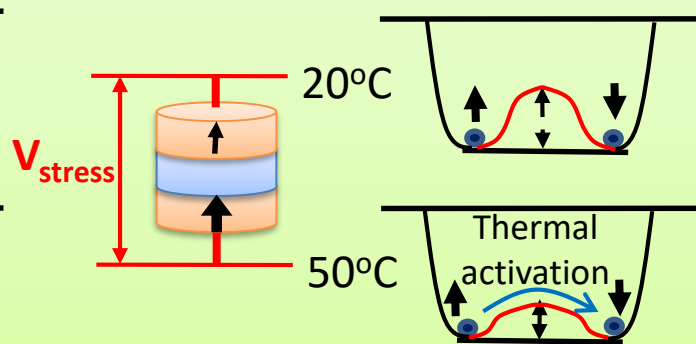
Linear

$V_C$  (VC-MTJ)  
 $J_C$  (STT-MTJ)

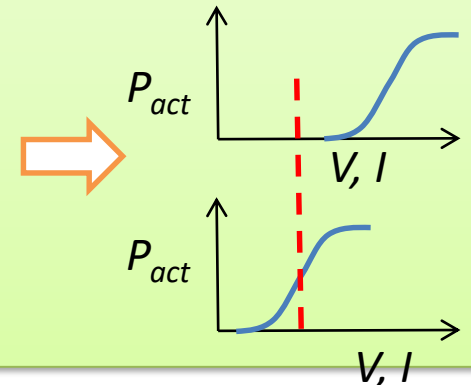
Retention time:  
10 years vs 10 hours



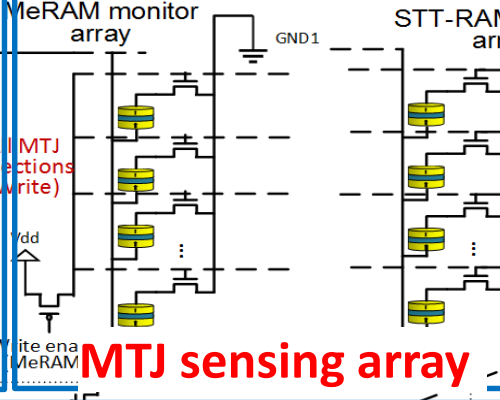
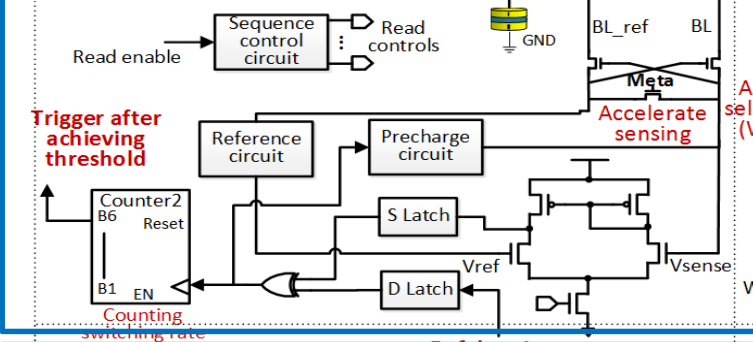
Retention time after stress  $V, I$   
100 $\mu$ s vs 10ns



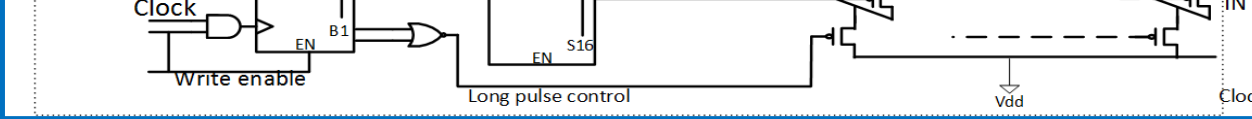
Activation rate after a period (e.g., 20ns)



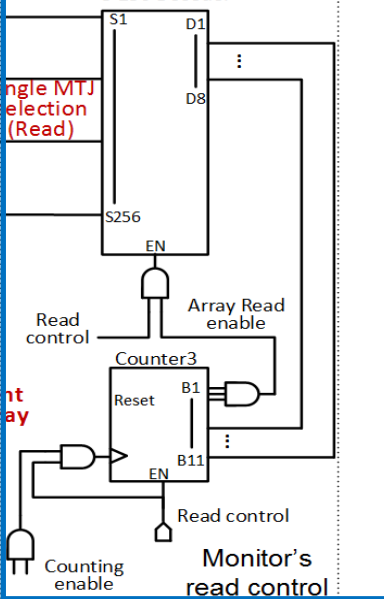
## Sensing and counting



## Stress voltage/current generation



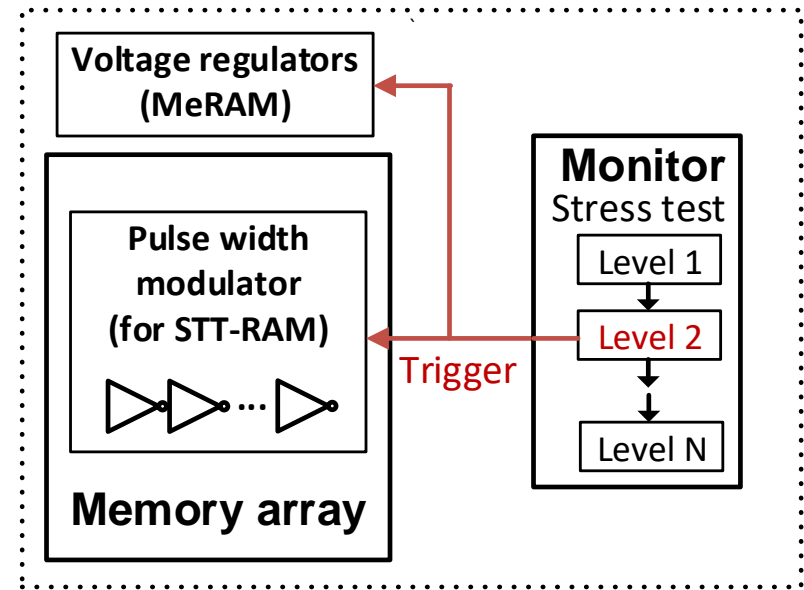
## Decoder for MTJ selection



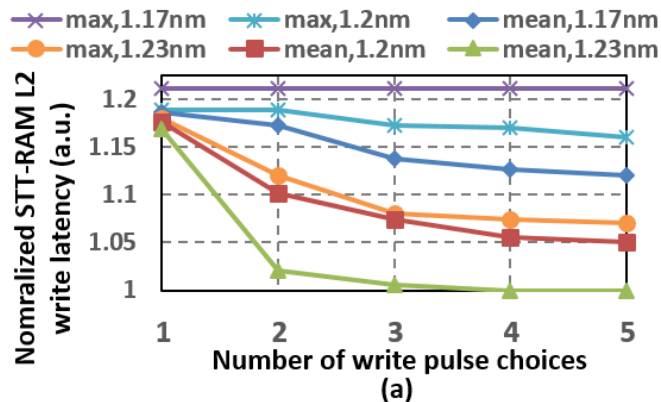
Monitor	Latency	Accuracy	Energy	Area
C. Chung, et al	0.1ms	9°C	0.015μJ	0.01mm <sup>2</sup>
K. Woo, et al	0.2ms	3°C	0.24μJ	0.04mm <sup>2</sup>
P. Chen, et al	1ms	2°C	0.49μJ	0.01mm <sup>2</sup>
A. Aita, et al	100ms	0.1°C	13.8μJ	0.04mm <sup>2</sup>
this(STT)	1-10μs	10°C	0.12-1.2nJ	0.0005mm <sup>2</sup>
this(Me)	1-10μs	10°C	0.27-2.7nJ	0.0005mm <sup>2</sup>

# Application of the variation monitor - adaptive write

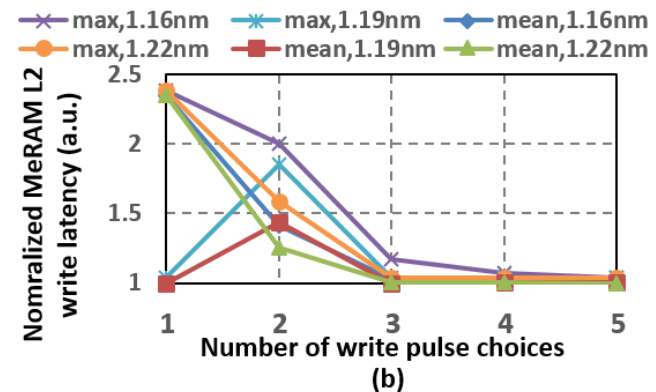
- Dynamically select optimal pulses for multiple-write<sup>1</sup>
  - Write latency variation minimization
    - Three write pulse choices are enough
    - 1.2X for 1-MB STT-RAM write latency improvement
    - 2.4X for 1-MB MeRAM write latency improvement



STT-RAM



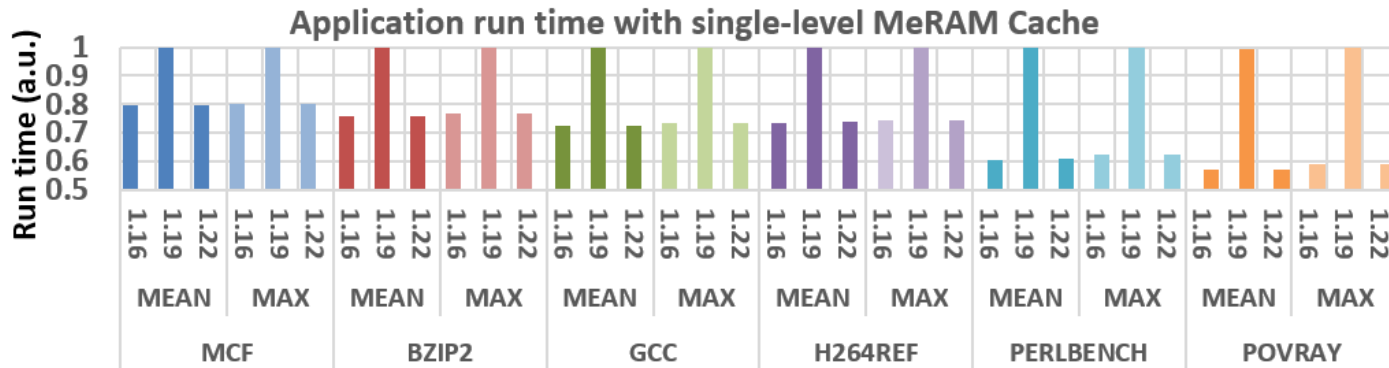
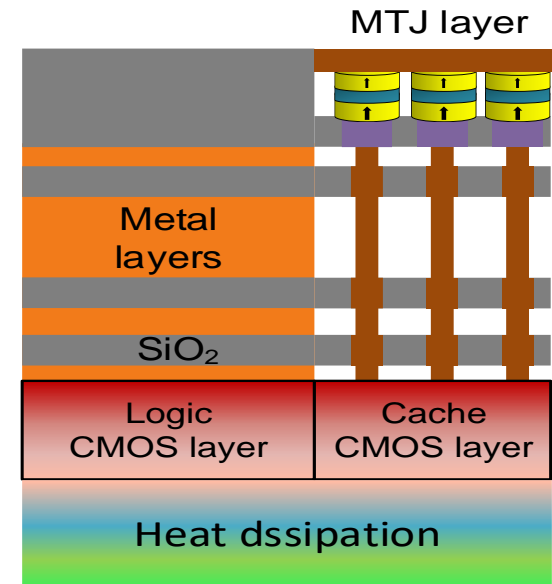
MeRAM



<sup>1</sup>H. Lee et al. TMAG (2015).

# Evaluation of adaptive write

- Experimental setup:
  - 32nm Single-core X86, 8-MB universal MRAM cache
- Simulations
  - MTJ switching simulation (experimentally verified physical models )
  - Circuit simulation (SPICE and NVSIM)
  - Architecture simulation (gem5)
  - Thermal simulation (Hotspot)
  - Power simulation (CACTI)
- 1.7X and 1.1X application run time improvement for processor with MeRAM and STT-RAM



(b)



# Conclusion

- The proposed variation monitor can sense combined wafer-level process and temperature variation
  - ***10X faster, 5X energy-efficient, and 20X smaller than conventional 65nm temperature monitor with same accuracy***
- Adaptive write scheme dynamically selects optimized write pulse through variation monitoring
  - MeRAM receives more benefit than STT-RAM
    - ***2.4X and 1.2X cache speed improvement for MeRAM and STT-RAM***
    - ***MeRAM suffers from more variation impact***
    - STT-RAM without multiple-write is expected to see much more improvement in both power and latency (future work)
    - 1.7X application run time reduction for processor with MeRAM cache
    - 1.1X application run time reduction for processor with STT-RAM cache
- **Thank you for your attention**